
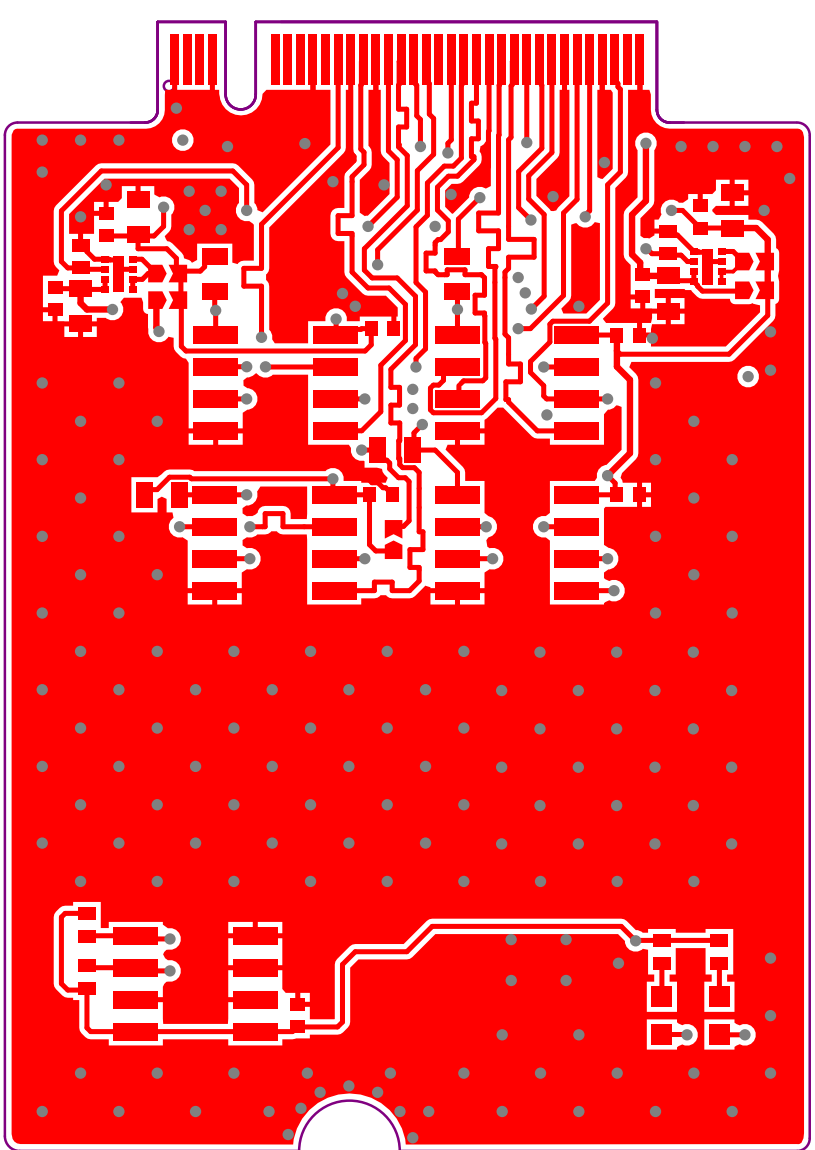

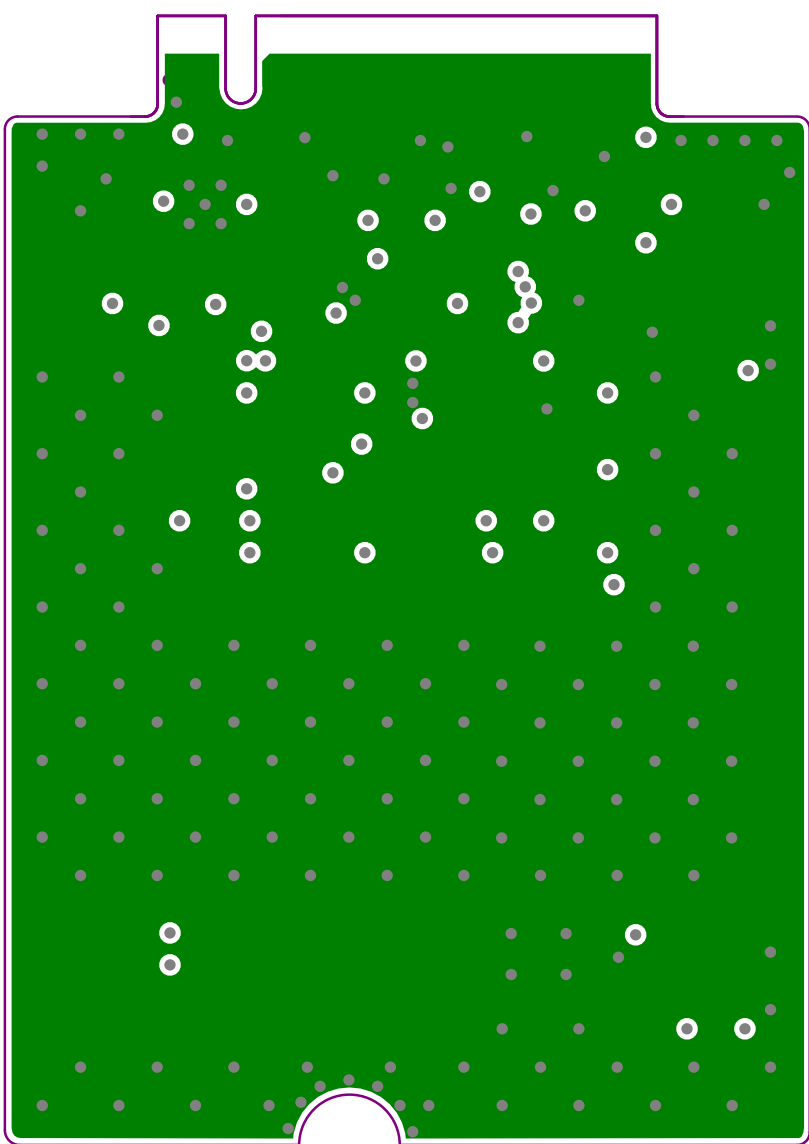



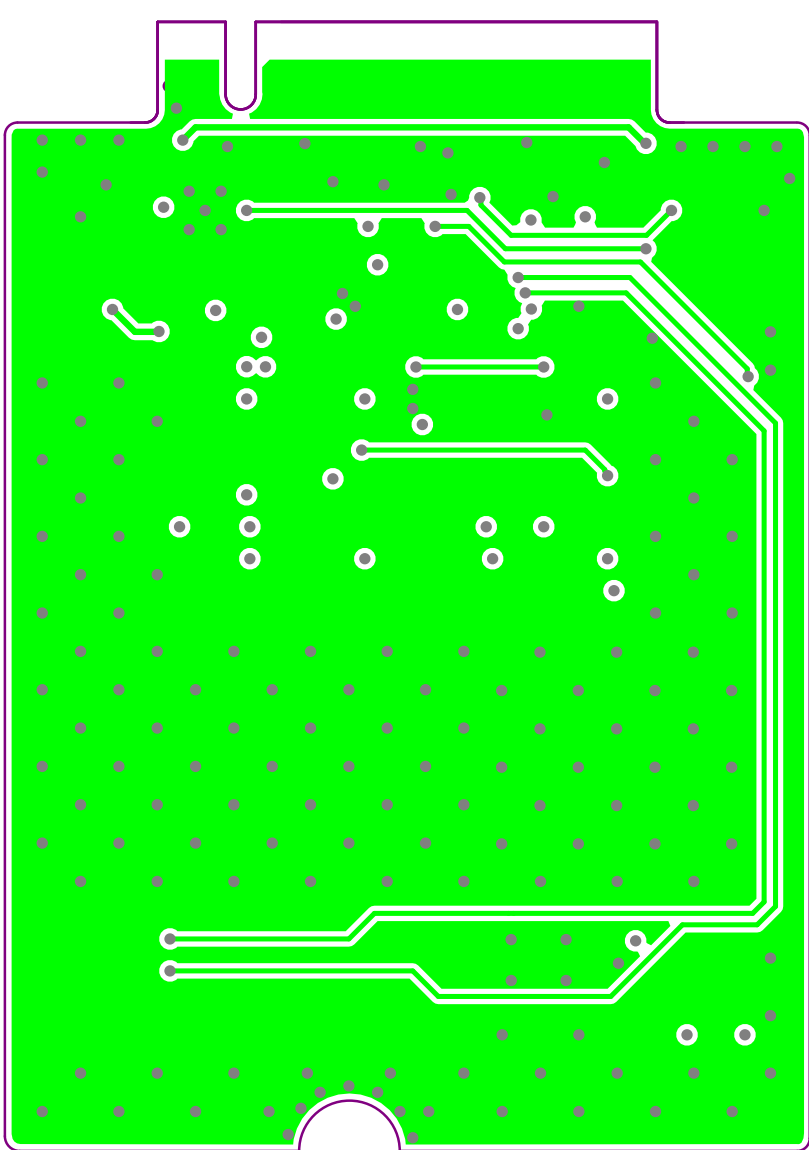
Project: M.2 Serial Memory QSPI		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	




Project: M.2 Serial Memory QSPI		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	




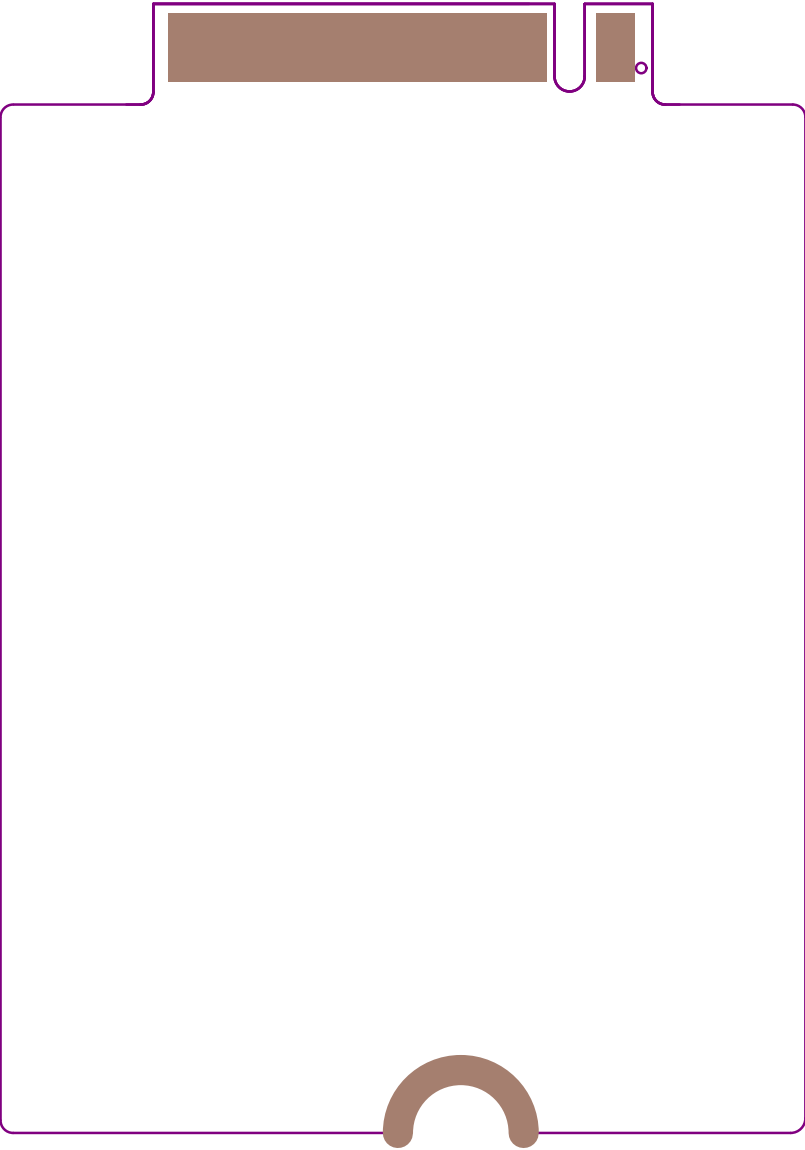
Project: M.2 Serial Memory QSPI		
Layer: Layer 1	Gerber: .G1	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	




Project: M.2 Serial Memory QSPI		
Layer: Layer 2	Gerber: .G2	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	




Project: M.2 Serial Memory QSPI		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	



Project: M.2 Serial Memory QSPI		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	



Project: M.2 Serial Memory QSPI		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.018mm	3.5	
1	Top Layer		0.036mm		
	Dielectric 2	PP-006	0.109mm	4.1	
2	Layer 1	CF-004	0.030mm		
	Dielectric 1	FR-4	0.410mm	4.8	
3	Layer 2	CF-004	0.030mm		
	Dielectric 3	PP-006	0.109mm	4.1	
4	Bottom Layer		0.036mm		
	Bottom Solder	Solder Resist	0.018mm	3.5	
	Bottom Overlay				
Total board thickness:			0.796mm		

THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY)

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

☐ IMPEDANCE CONTROL :

G. THROUGH VIA :

☒ STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ TG-150

☐ TG-140

☐ WHITE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☐ RED

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

☒ BLUE

☐ Blue ink PANTONE 2955

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

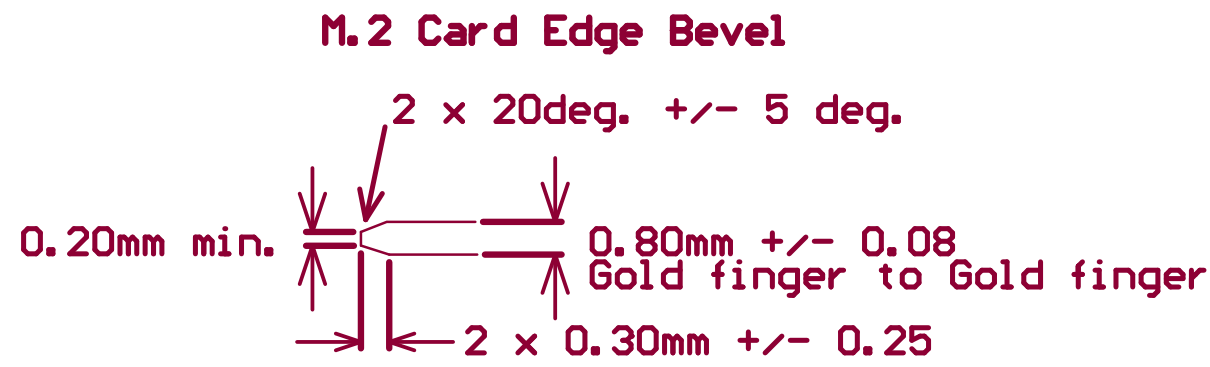
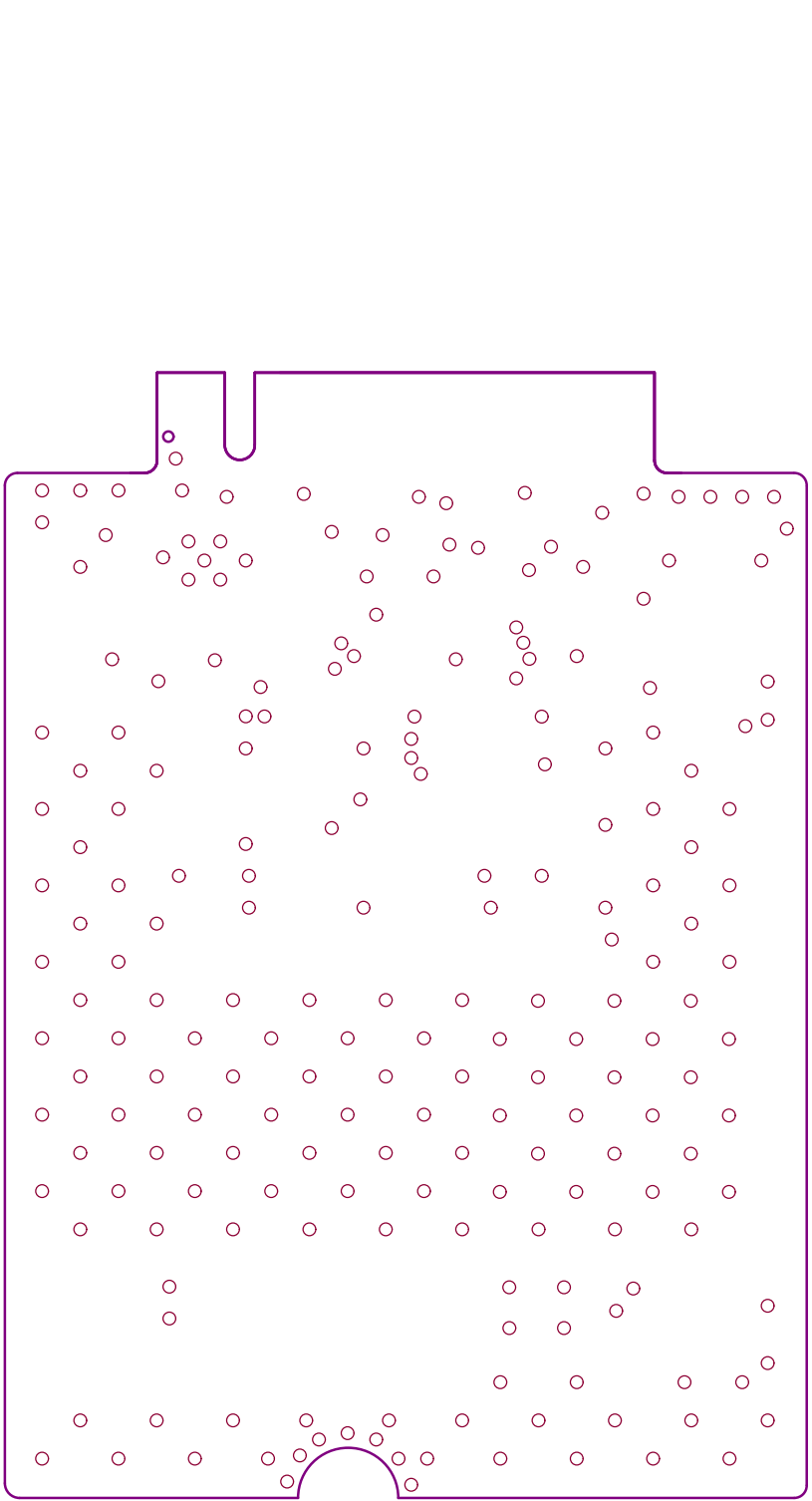
PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1
LEVEL "B"


MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.200mm
GAPS : 0.120mm



Impedance control is 50 Ohms +/- 5% on all tracks 0.20mm width on top and bottom layers

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
○	210	7.87mil (0.20mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v45h20m0mx0				-	-
	210 Total												

Project: M.2 Serial Memory QSPI		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	MB1928	
Date: 22-MAY-25	Rev: C	